

Future Technology Devices International Ltd. Technical Note TN_108

VINCULUM Chipset Feature Comparison

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This technical note compares the features of VNC1L and VNC2 devices.



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1 Introduction

VII is the next generation device in the Vinculum family. The VNC2 device will build on the successes of the original VNC1L device.

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2 Chipset summary

2.1 VNC1L

VNC1L is a single chip embedded USB host controller IC device. The entire USB protocol is handled on the chip.

The device supports two independent USB 2.0 Low-speed/Full-speed USB host ports with integrated pull-up and pull-down resistors.

The device supports USB suspend and resume with 3V3 interface.

2.2 VNC2 - Second generation device

VNC2 expands on the abilities of the VNC1L devices with more memory and a faster processor. It also has a debug port and is supported with a suite of software development tools available to customers to create their own firmware.

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3 Chipset comparison tables

3.1 VNC1L vs VNC2

The following table highlights and compares the features of VNC1L and VNC2 devices.

FEATURE	VNC1L	VNC2
MECHANICAL		
Package	48 pin LQFP	64 pin LQFP (Also aiming at 32 pin and 48 pin cut down versions)
Temperature	-40 to +85C	-40 to +85C
ELECTRICAL		
VCC	3V3	3V3
VCCIO	5V tolerant 3V3	5V tolerant 3V3
CLK source	12MHz (external)	12MHz (external)
СРИ	8-bit Harvard architecture	16-bit Harvard architecture
INTERFACING		
USB ports	2	2
UART port	1	1
SPI slave port	1	2
SPI master port	0	1
FIFO monitor port option	1	1
Debug port	0	1
FIRMWARE		
Precompiled firmware	YES	YES
Tools for creating own firmware	NO	YES
MEMORY		
DATA RAM	4k x 8 (4kbytes)	4k x 32 (16kbytes)
E-FLASH	64k x 8 (64kbytes)	128k x16 (256kByte)
USB MODES		
Speed	Full / low	Full / low
Transfer modes	Bulk / Interrupt	Bulk, interrupt, isochronous
CONFIGURATION PORTS		



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UART	YES	YES
USB	YES (after initial programming)	YES
SPI	NO	YES
FIFO	NO	YES
DEBUG PORT	N/A	YES

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5 Appendix A- Definitions

5.1 Terms description

Terms	Description
UART	Universal Asynchronous Receiver Transmitter
FIFO	FT245 style asynchronous FIFO interface
SPI	Serial Peripheral Interface
USB	Universal Serial BUS

5.2 Links to datasheets

Chipset	Web link to datasheet
VNC1L	http://www.vinculum.com/documents/datasheets/DS VNC1L V201(FT 000030).pdf



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6 Appendix B - Revision History

Revision History

Version draftInitial draft13th March, 2009Version 1.0Initial rev1.021st May, 2009Version 1.1Released to the Web26th Feb, 2010